

WD Packaging Job Description - Staff Engineer, Packaging Engineering

As a packaging simulation engineer, you will work in the global Packaging R&D group on modeling and simulation across semiconductor packaging, flash memory product, and host levels. In this position, you will be responsible for influencing package and product design by addressing structural integrity and reliability issues in particular and advancing the technology of semiconductor packaging in general. Scope is to address all mechanical aspects of packaging technology and associated material and process interactions. Focus will be on solutions to meet increased demands for small form factor packages with thinner and more fragile chips, denser and finer interconnects and higher power. Candidate will be responsible for the modeling and simulation of mechanical responses of the IC package and flash product using analytical and computational tools. This position will interface with package & product design, electrical and physical characterization, lab testing, failure analysis, assembly R&D and other process teams. Solid background in applied mechanics and computational techniques is required. In-depth knowledge of IC packaging is highly desired.

Qualifications:

- Ph.D./Master in mechanical engineering plus >5 years of relevant industrial experience.
- Solid knowledge through academic coursework or experience required in mechanical engineering of IC packaging and related areas.
- Strong background in applied mechanics with emphasis on both analytical and computational methods.
- Broad knowledge of various material types such as **ceramic and glass, polymers and metals (e.g., solder) and their mechanical behaviors.**
- Working knowledge in using commercial **FEA packages.**
- Working knowledge in scientific programming.
- Good understanding of general semiconductor packaging processes, materials, technology and trends, such as substrate design and manufacturing, molding, wire-bonding, die attach, flip chip, etc.
- Strong oral and written communication skills.
- Demonstrated strong work ethic.
- Ability to work in a team environment and interact with other engineers to define and implement numerical and lab experiments for feasibility and validation of concepts and solutions to support new package technology development.

If interested, please contact Dr. Lau at sean.lau@wdc.com. Thanks for passing this along.